

1 ABSTRACT OF THE DISCLOSURE

2 Integrated Circuit Package With Overlapping Bond Fingers

3 An integrated circuit package comprises a set of bond fingers for connecting
4 wire bonds from the chip, the bond fingers being placed overlapping on a
5 transverse axis from the chip and extending inwardly and outwardly from
6 vias positioned at different positions along the transverse axis, so that wire
7 bonds connected to adjacent fingers have the same length.